

MEMS Deformable Mirrors Advancements for Space Telescopes



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Peter Ryan (1), Mark Horenstein (2) and Thomas Bifano
(1,2)**

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Boston University, Boston, MA 02215**



SPIE

**Mirror Technology
Days 2012
August 1, 2012
Rochester, NY**

**NASA SBIR PHASE I/II
Approved for Public Release by NASA per NPR 2200**



Outline

- MEMS DM technology drivers and architecture overview
- Examples of MEMS DM in astronomical applications
- Current MEMS development programs
- Next steps
- Conclusions





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Why MEMS for DMs?

Design

Easier to scale to larger arrays (~**4000**) needed for large telescope AO

Smaller size/weight/power needed for space-based AO

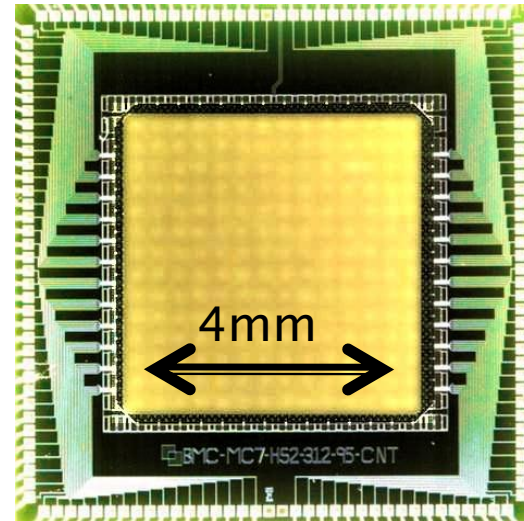
Manufacturability

10x Lower cost (~**\$150/actuator**) than macroscale devices

Batch produced (vs. manual assembly)

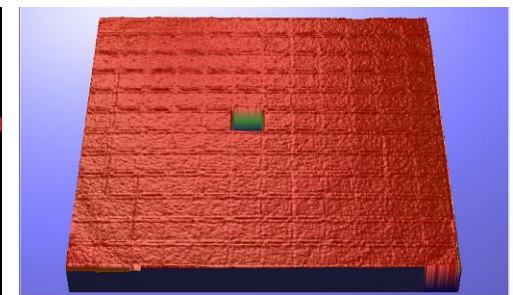
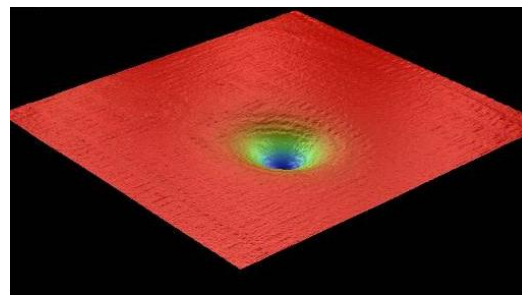
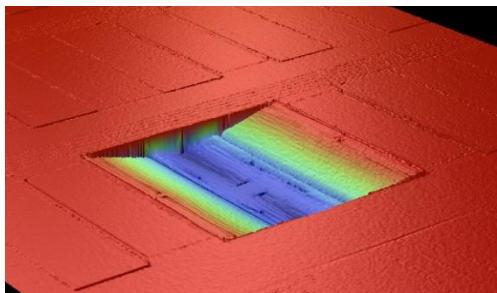
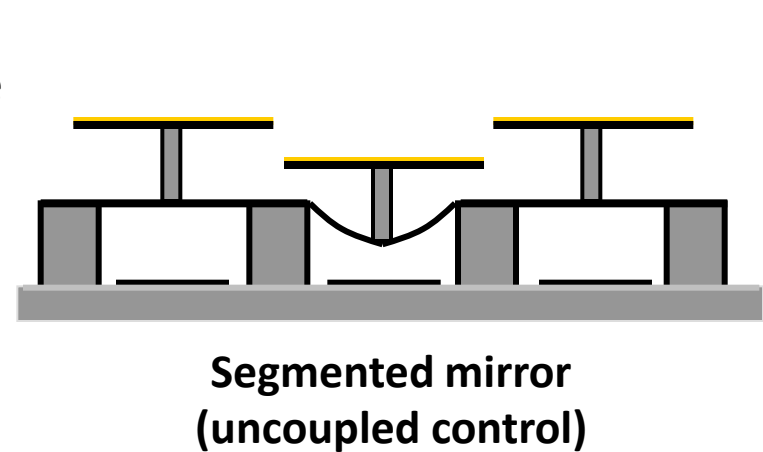
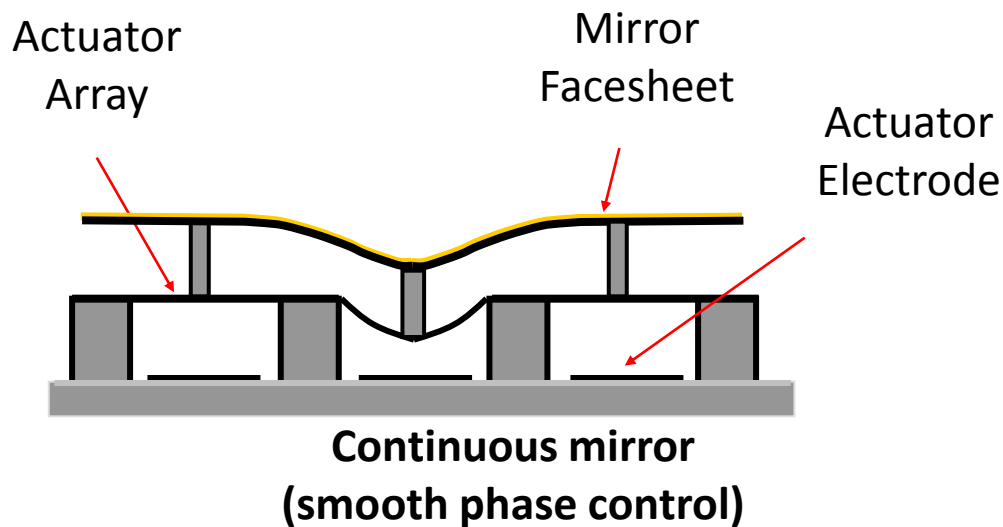
Performance

- No hysteresis
- Reliable
- Fast temporal response
- Predictable
- Compact
- Low Power
- Polarization and wavelength insensitive



The advantages of these MEMS DMs have inspired a new generation of imaging instruments, and laser beam control systems

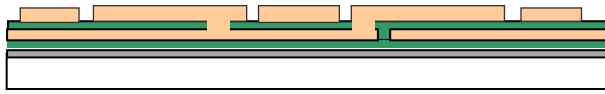
Silicon Surface Micromachined MEMS DMs



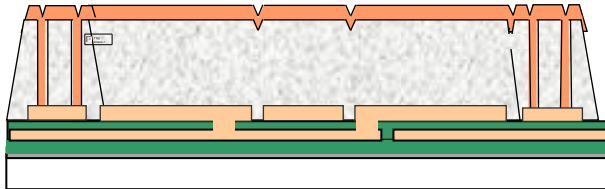


MEMS DM Fabrication

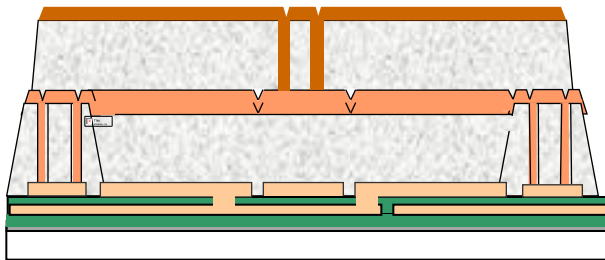
(deposit, pattern, etch, repeat)



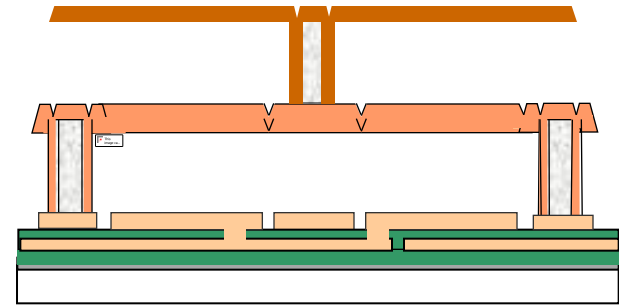
Electrodes & wire traces:
polysilicon (conductor) & silicon nitride (insulator)



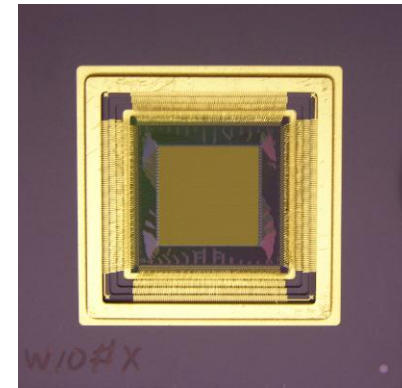
Actuator array:
oxide (sacrificial spacer) and polysilicon (actuator structure)



Mirror membrane:
oxide (spacer) and polysilicon (mirror)

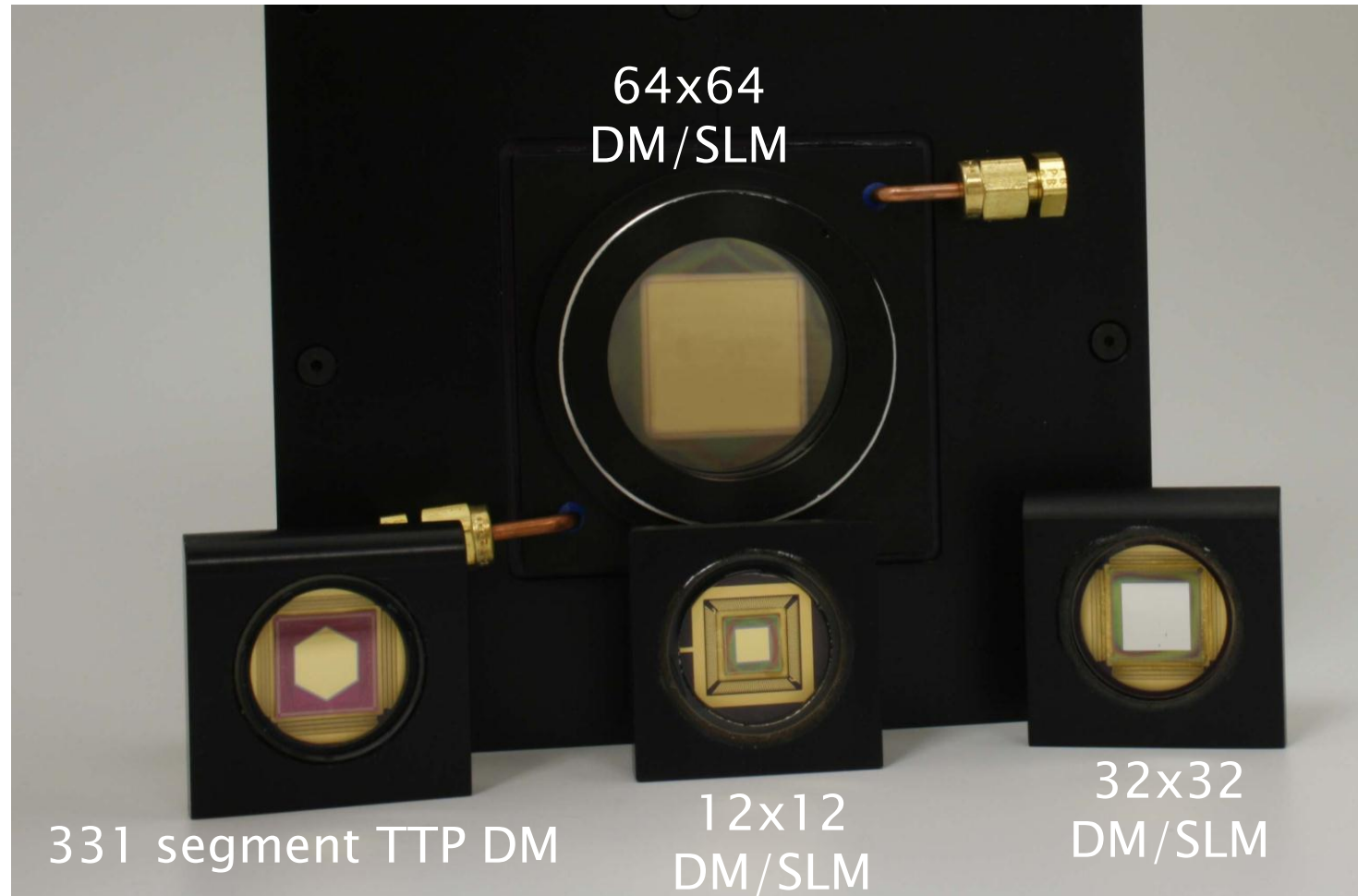


MEMS DM:
Etch away sacrificial oxides in HF, and
deposit reflective coating



Electrical Interconnects:
Die attach and wirebond to ceramic
chip carrier

BMC Deformable Mirrors





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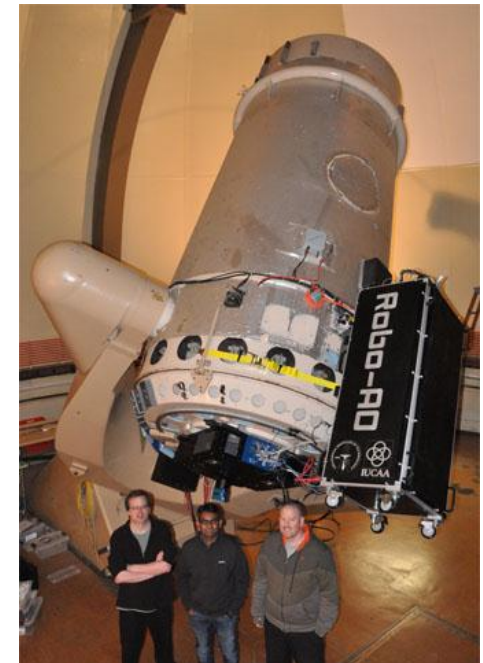




Observatories using BMC DMs

- ▶ Lick Observatory (VILLAGES):
 - 140DM used for visible AO on 1m telescope (2007)
 - Visible AO using Kilo DM on 3m telescope (on-sky 2013)
- ▶ Gemini (GPI): High contrast AO system using a 4k DM (on sky 2013)
- ▶ Subaru Telescope (SCExAO): Subaru Coronagraphic Imager with Extreme Adaptive Optics using Kilo DM (2011)
- ▶ Palomar Observatory (Robo-AO): Low-cost, autonomous, integrated laser adaptive optics system using 140 element DM (2011)

DMs in many other test beds around the world



Robo-AO

Robo-AO

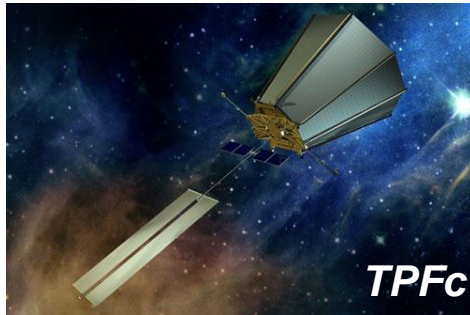
Observation of Saturn in the i-band ($\lambda = 700 - 810 \text{ nm}$)
from the Palomar Observatory 60" telescope
using the Robo-AO laser adaptive optics system

May 10th, 2012 6:41 UTC

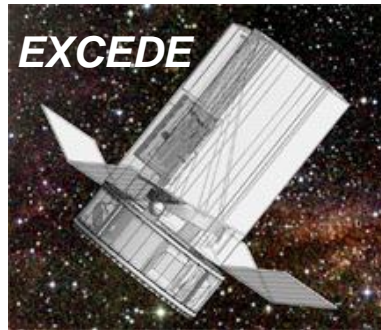


MEMS DMs in Space Telescopes

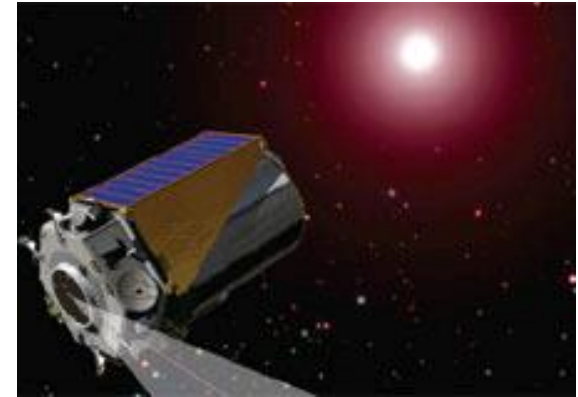
- ▶ Correction of static and slow moving (thermal) aberrations in space-based optical imaging systems
 - Astronomy – Direct Planet Detection
 - High Contrast Imaging
 - Reconnaissance
 - Correction of surface figure errors in Light weight primary mirrors



*Terrestrial Planet Finder
Coronagraph*



*The Exoplanetary Circumstellar
Environment and Disk Explorer*



*Extrasolar Planetary Imaging
Coronagraph*

*Space Infrared Telescope for
Cosmology and Astrophysics*

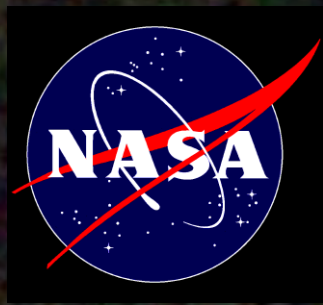


SPICA

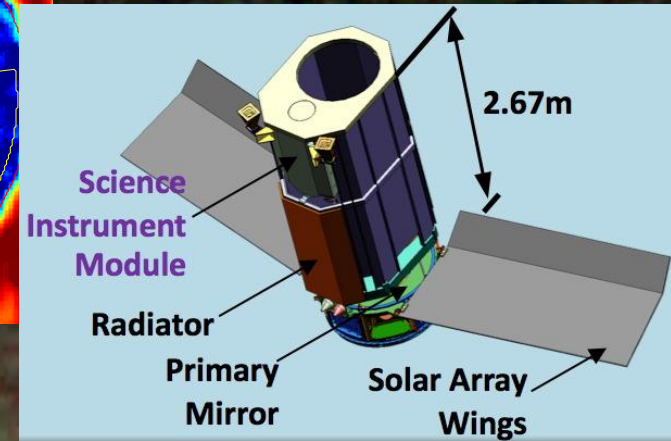
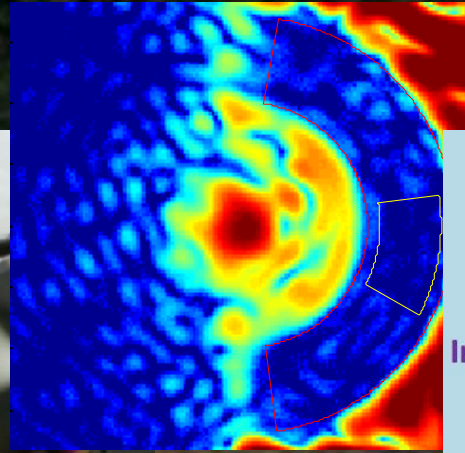
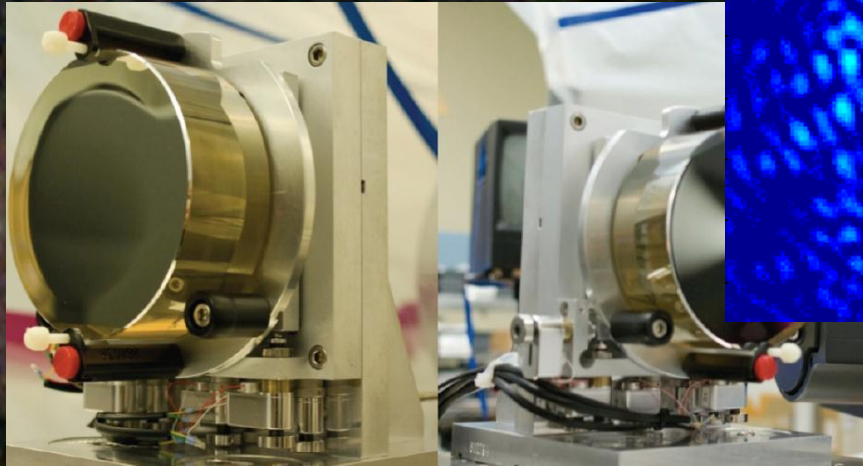


PECO

Pupil-mapping Exoplanet Coronagraphic Observer



Development of the Phase Induced Amplitude Apodization Coronagraph for an Explorer Mission

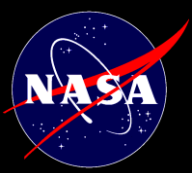


Ruslan Belikov, Eugene Pluzhnik, Fred C. Witteborn, Dana H. Lynch,
Thomas P. Greene, Peter T. Zell
(NASA Ames Research Center)

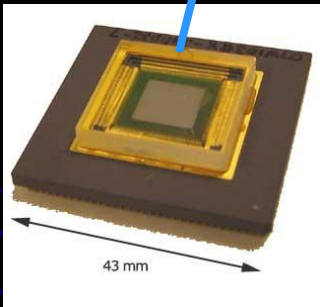
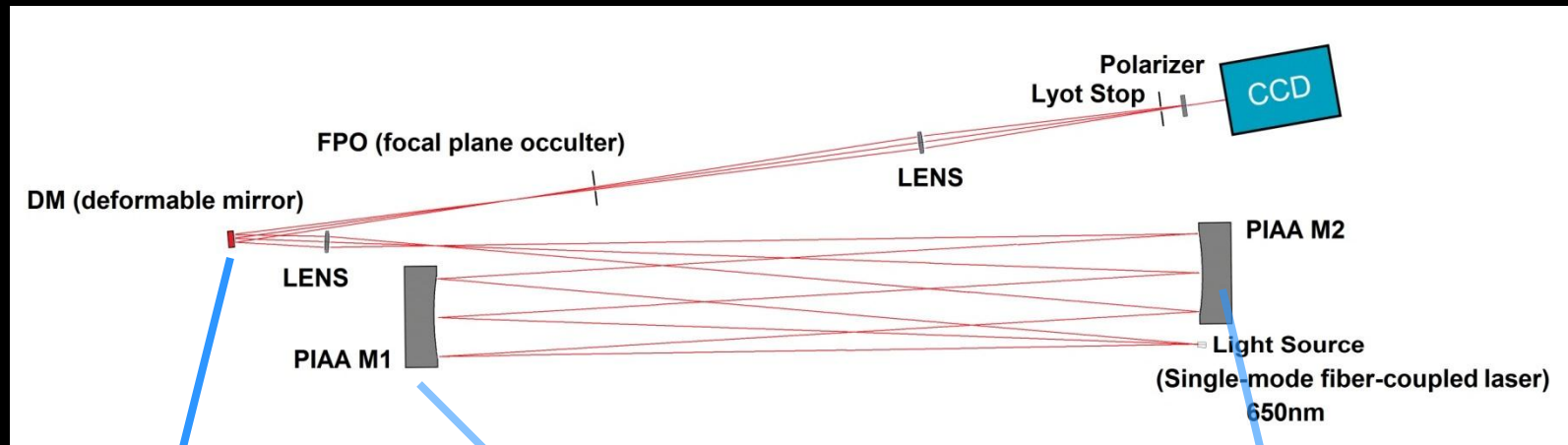
Glenn Schneider, Olivier Guyon
(University of Arizona)

Domenick Tenerelli, Alan Duncan, Rick Kennedy
(Lockheed Martin Space Systems Company)

July 29, 2012



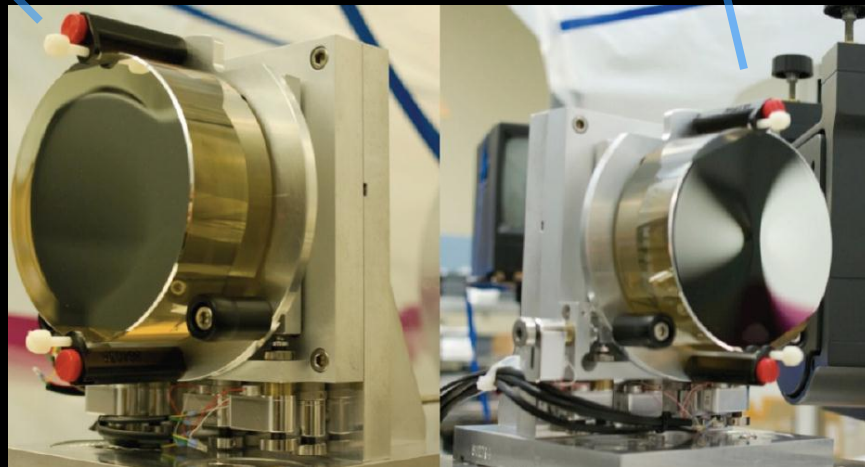
Experiment



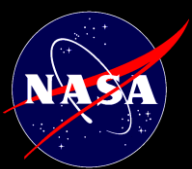
PIAA Coronagraph

Boston Micromachines
Deformable mirror (32x32)

Wavefront control uses
a combination of
(EFC) and Speckle Nulling



Broadband-capable PIAA mirrors
made by L-3 Tinsley



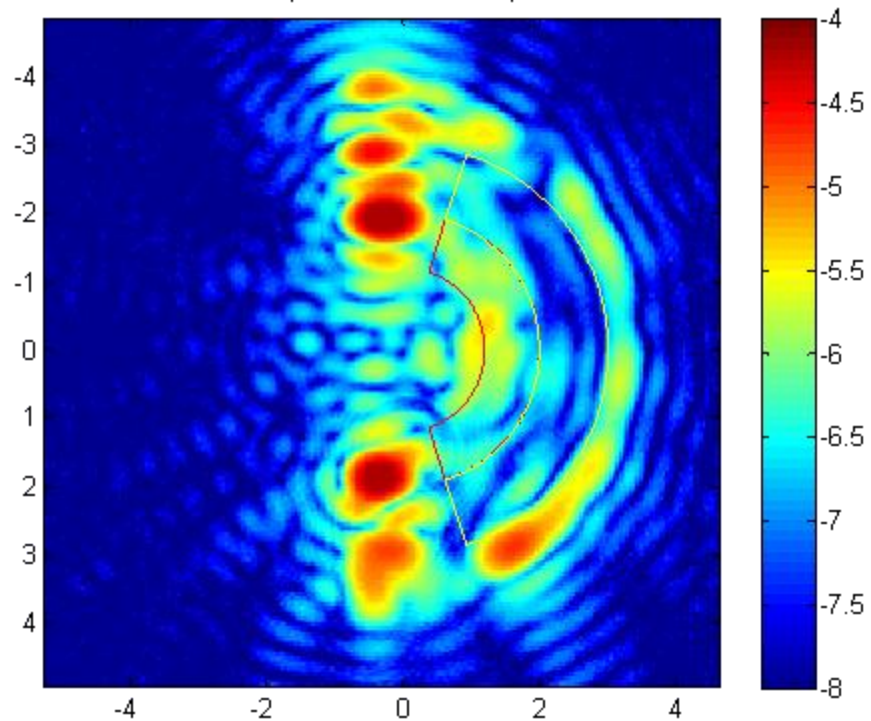
Results

(655nm light)

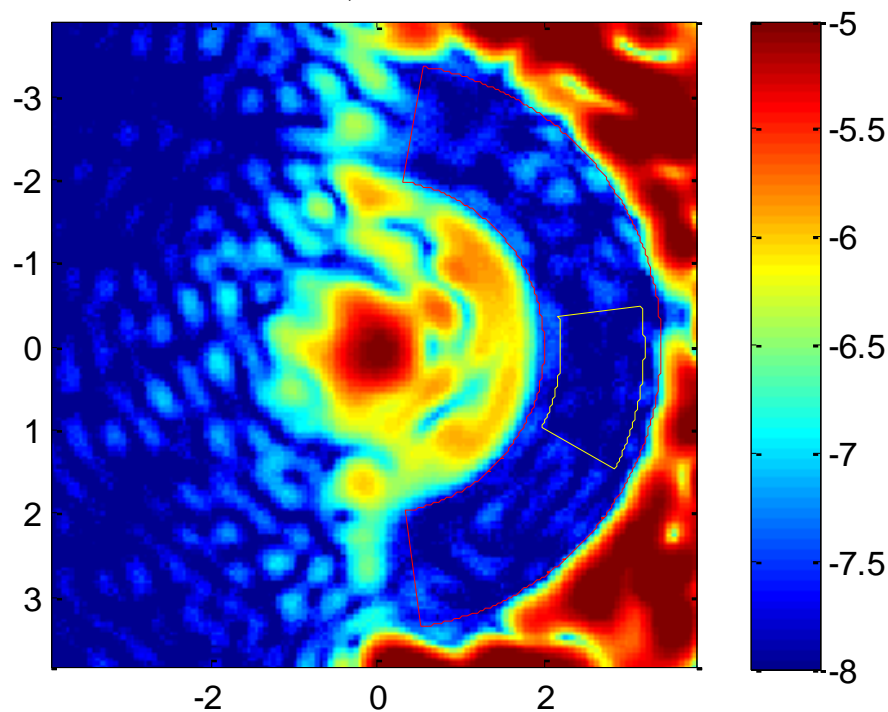
$8e-7$, 1.2-2.0 λ/D

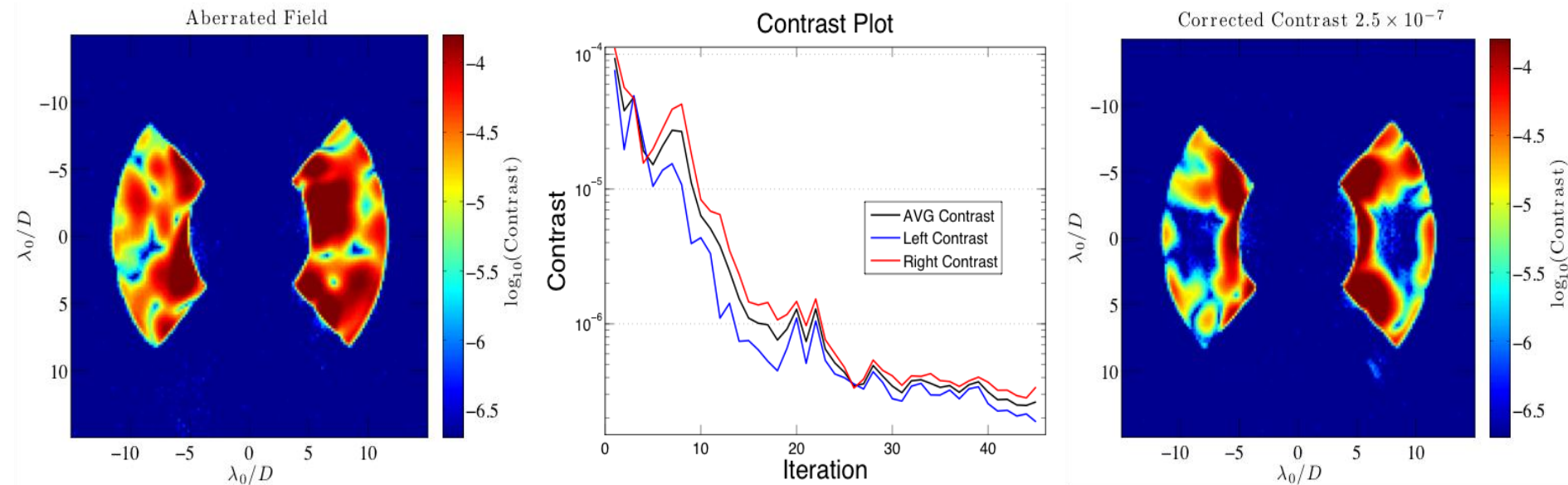
$1.9e-8$, 2.0-3.4 λ/D

mean: $8.47e-007$, median: $6.34e-007$, 1.2 - 2.0 I/D
mean: $1.76e-007$, median: $1.07e-007$, 2.0 - 3.0 I/D



$1.93e-008$, 2.0 - 3.4 I/D
 $9.25e-009$, 2.2 - 3.2 I/D





2.5×10^{-7} in 43 iterations
Fewest required measurements to date in
Princeton's HCIL

- Only one measurement update required per iteration
- Noisy start highlights the sensitivity of estimate to probe quality

Jeremy Kasdin and Tyler Groff, Princeton University



Good, but not good enough

NASA Wants

- ▶ More actuators for better wavefront control
- ▶ Proven reliability and protection against single point failures
- ▶ Better surface finish
- ▶ Reduction in size, weight, and power



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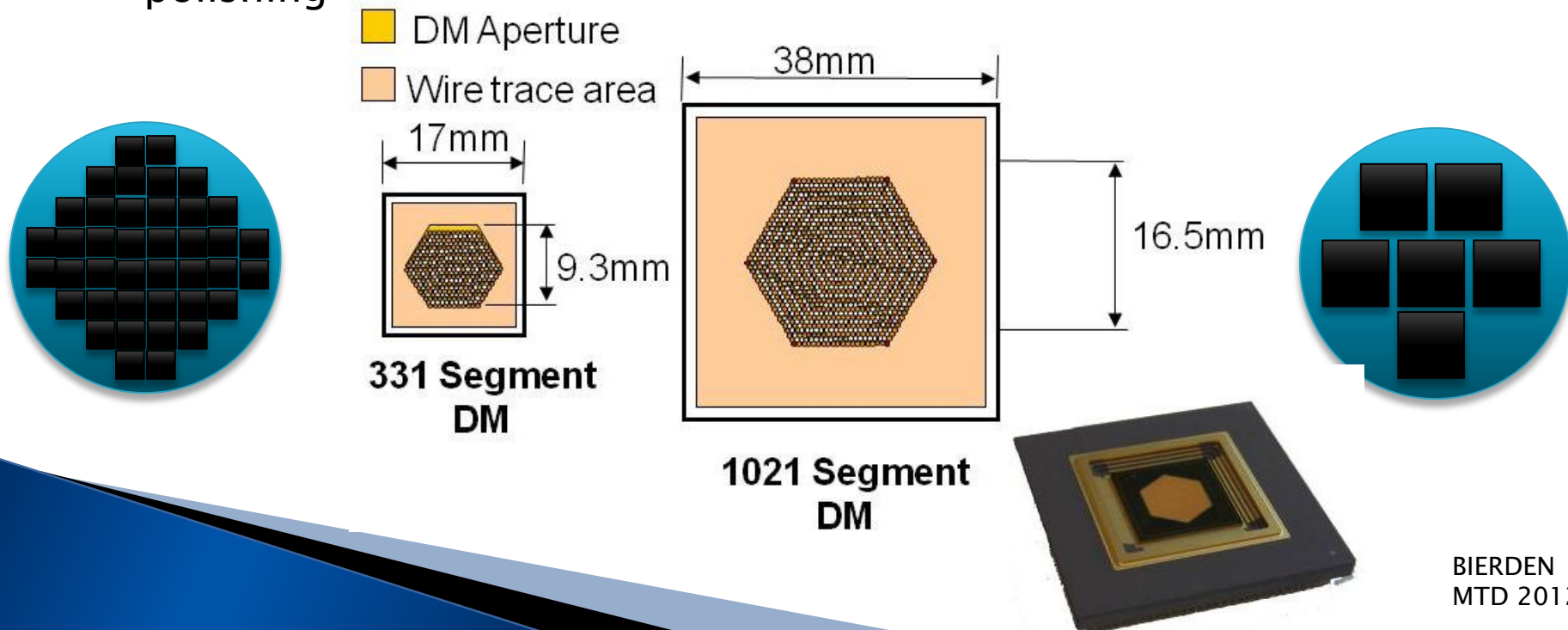
Enhanced Fabrication Processes Development for High Actuator Count Deformable Mirrors

SBIR Phase II
Contract # NNX11CB23C

1021 Element Tip-Tilt-Piston MEMS DM



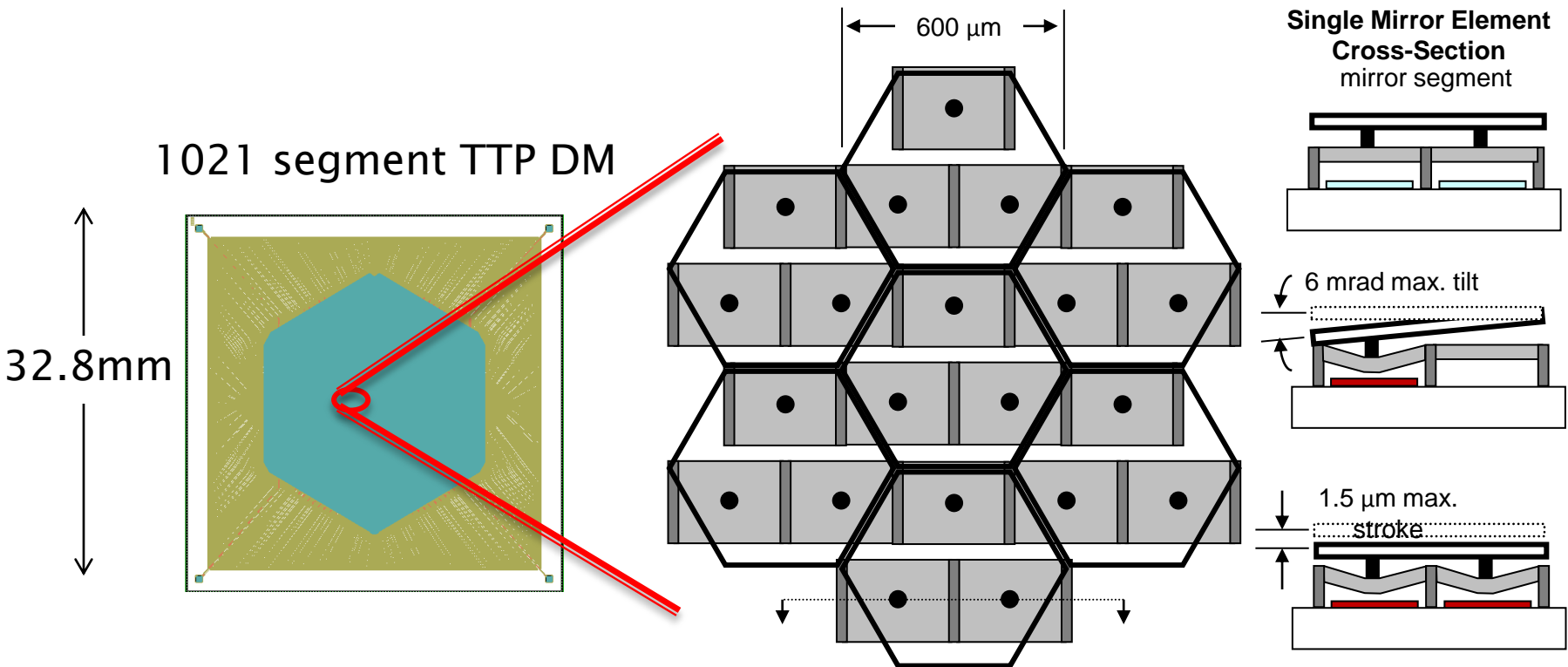
- ▶ Scale up mirror segments/actuators from 331/993 to 1021/3063
- ▶ Device architecture and fabrication process fundamentally scalable
- ▶ Challenge:
 - Managing inherent microscopic manufacturing defects (function of die area)
 - Controlling surface figure errors resulting from substrate bow and polishing



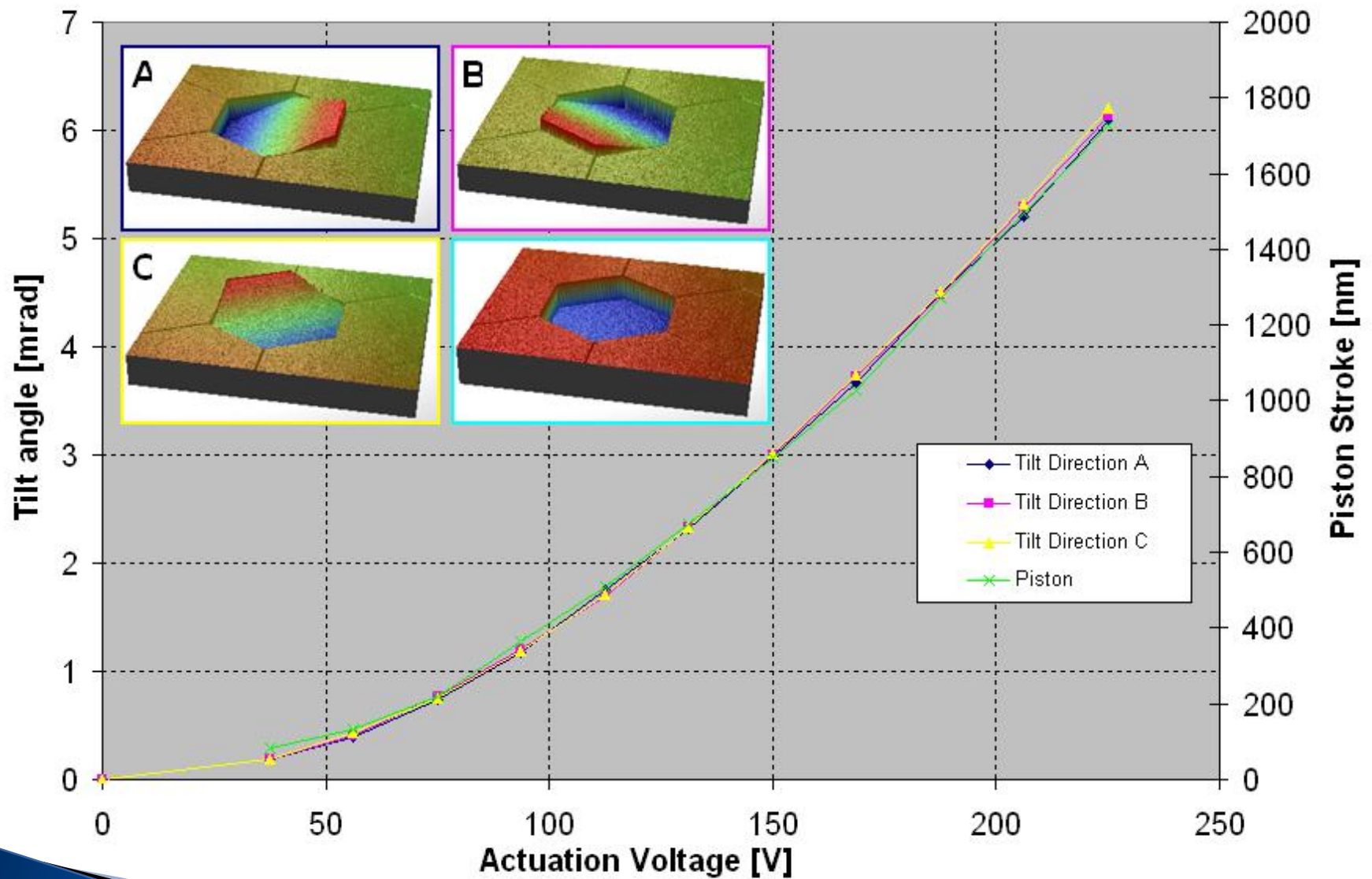


3063 Actuator DMs

- ▶ Under development for astronomical instrumentation

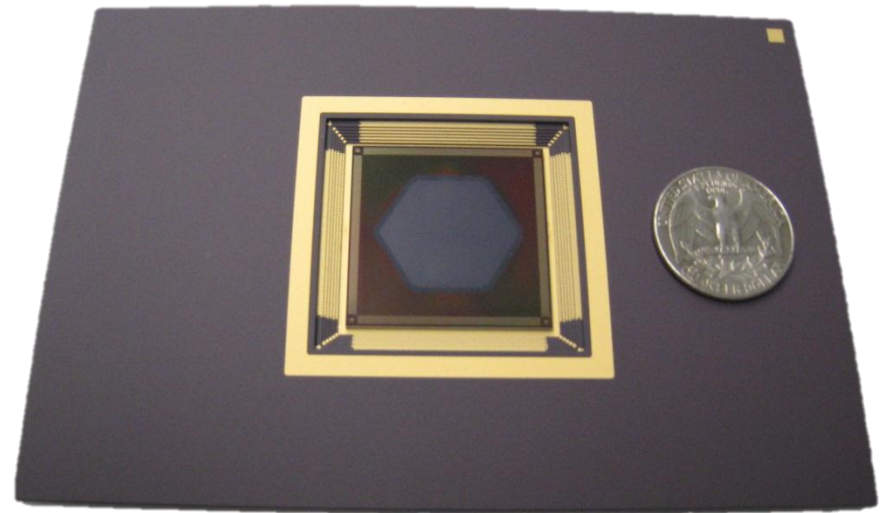


Electromechanical Performance - Tip/Piston



Tip/Tilt/Piston DM Development Status

- ▶ “Send ahead” wafer in house
- ▶ Will check actuation and yield
- ▶ Final fabrication by end of Q3





Enhanced Reliability MEMS Deformable Mirrors for Space Imaging Applications

SBIR Phase II

Contract # NNX12CA50C

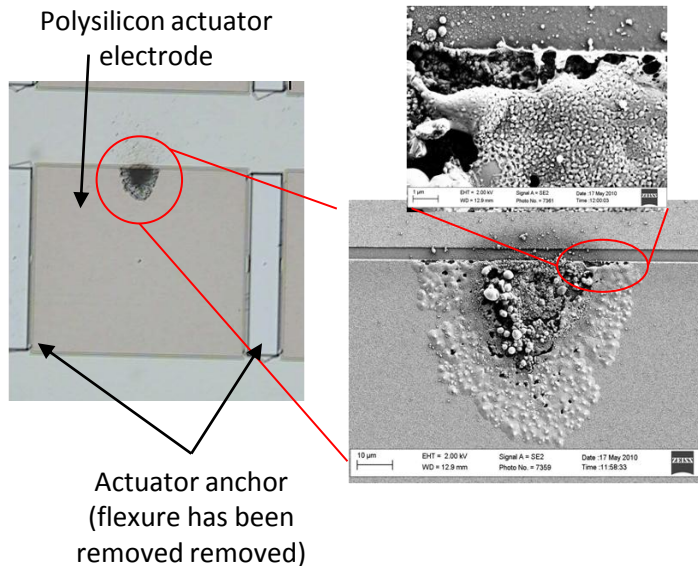
Enhanced Reliability DM Actuators



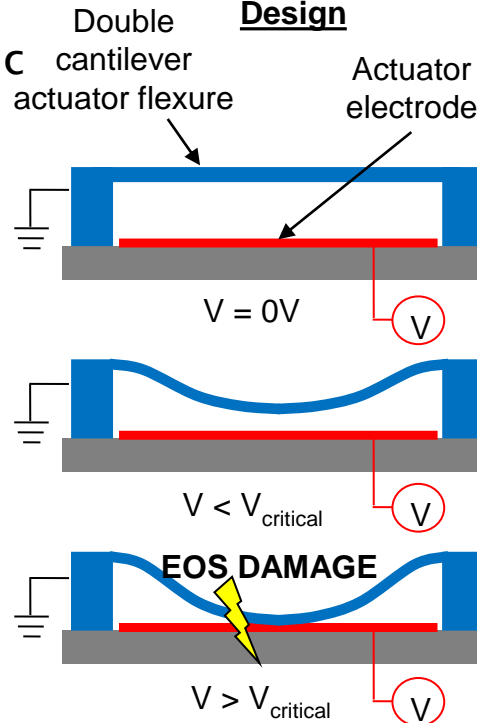
Although MEMS DMs have been demonstrated to be reliable under normal operating conditions the electrostatic actuators, space systems require redundant measures to ensure high reliability

MEMS DM system tolerant of electronic over-stress (EOS) demonstrated

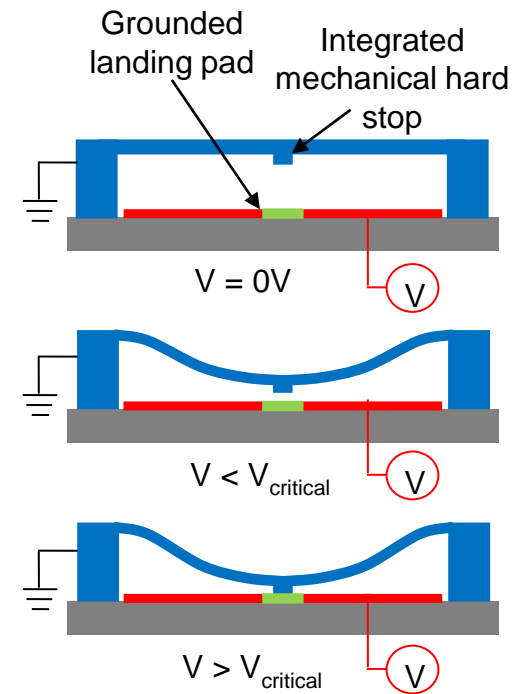
- Prevent irreversible failures due to actuator snap-through



Standard Actuator Design

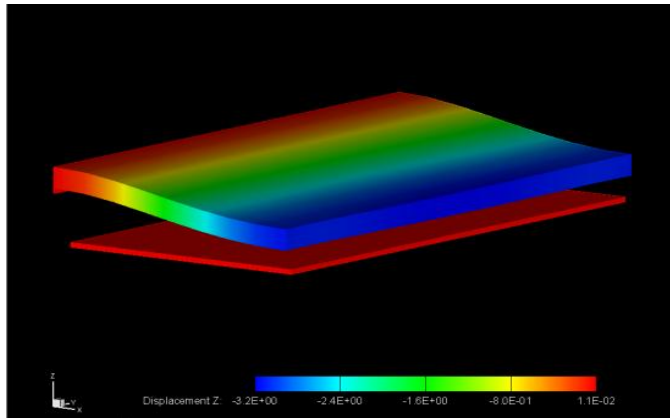


Enhanced-Reliability Actuator Design

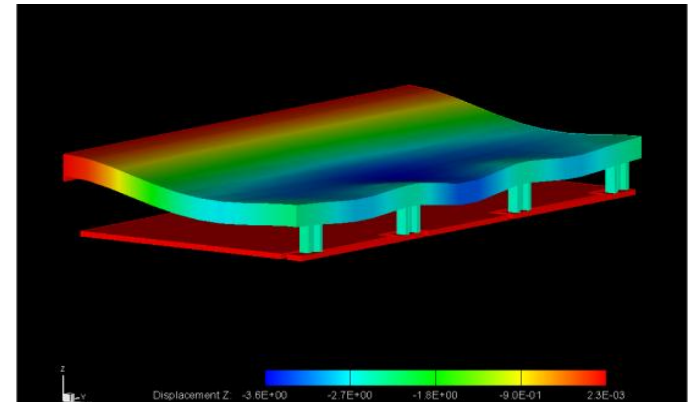


New Actuator Electromechanical Performance

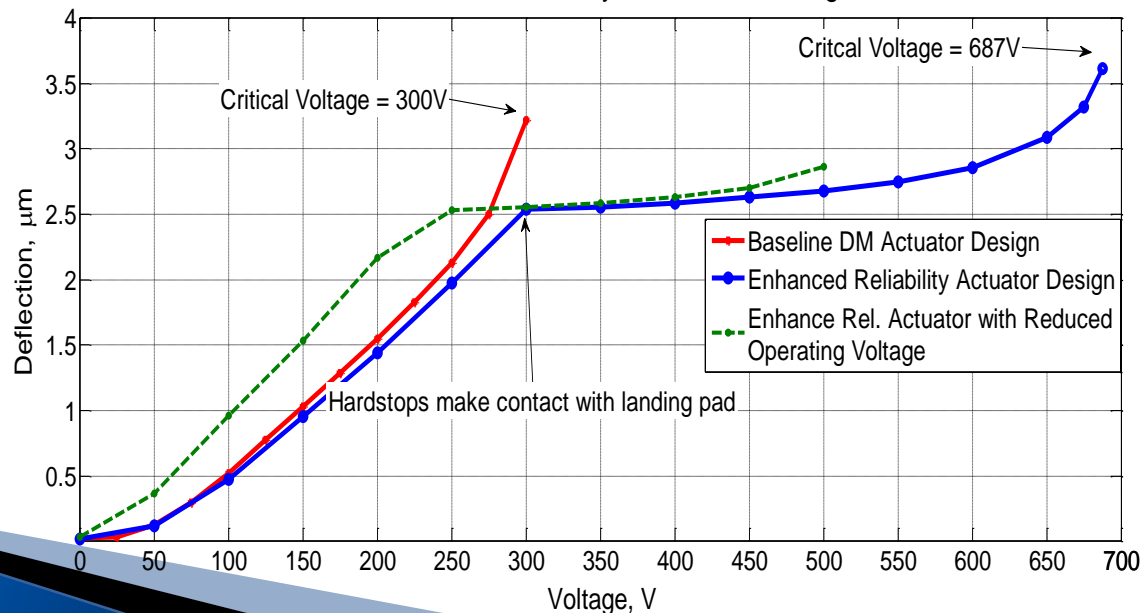
Baseline Actuator Design



Enhanced Reliability Actuator Design



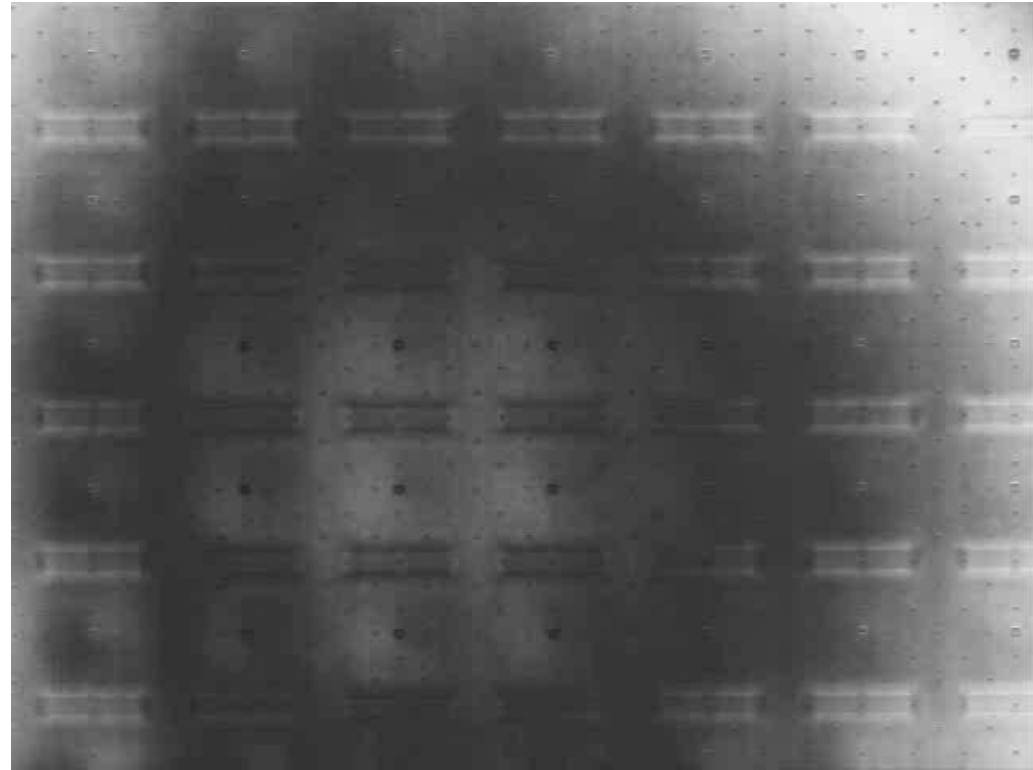
Electro-Mechanical Performance Comparison of Baseline DM Actuator and Enhanced Reliability DM Actuator Designs



Prevention of Snap-Through Related Damage



- ▶ Addition of current limiting elements further increases overall MEMS DM reliability
 - ▶ Eliminates high-current densities at snap-through

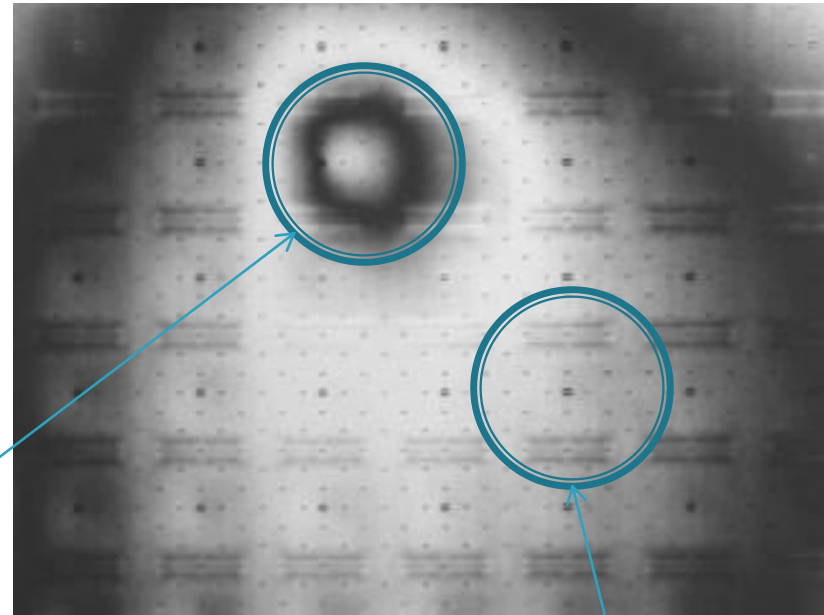
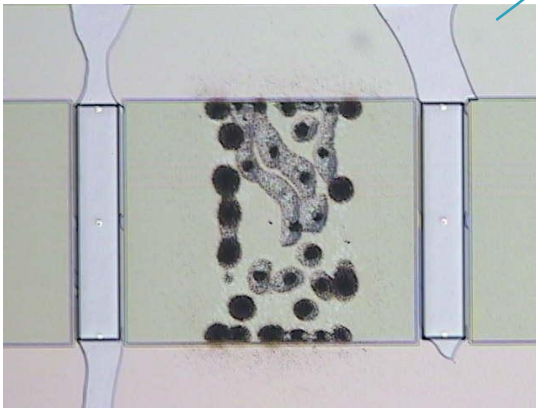


Prevention of Snap-Through Related Damage

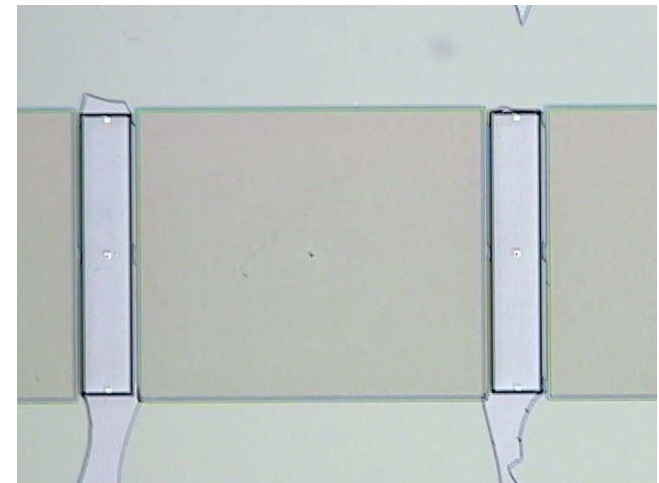


- ▶ Addition of current limiting elements further increases overall MEMS DM reliability
 - ▶ Eliminates high-current densities at snap-through

Without Current Limiting electronics



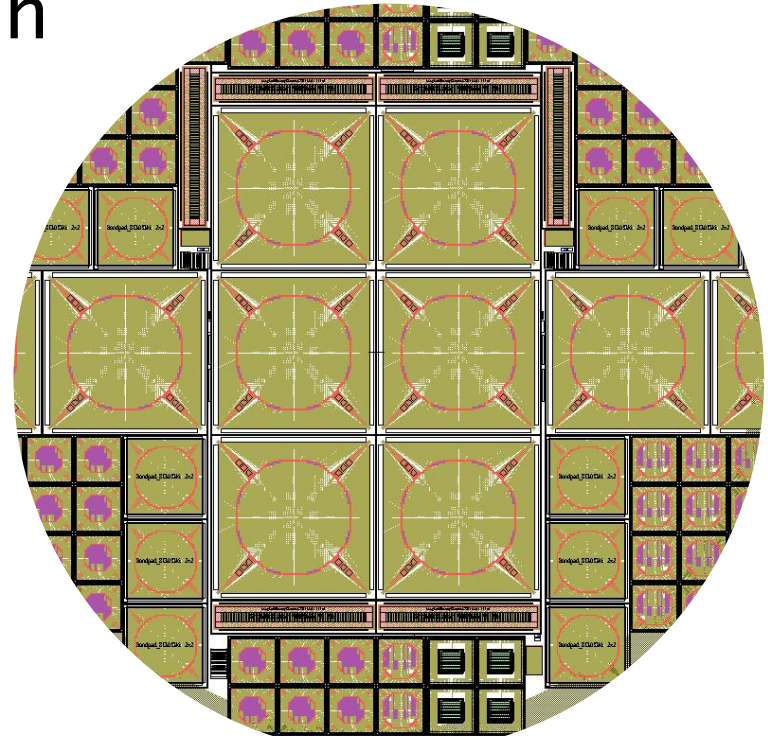
With Current Limiting electronics





New Layout Completed

- ▶ Incorporates new enhanced reliability design
- ▶ Includes 2048 actuator mirrors
- ▶ 48 actuators across aperture
- ▶ 300um and 400um pitch
- ▶ Fabrication to begin in ~1 month
- ▶ Completion in Q2 2013





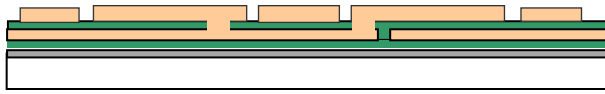
Topography improvements in MEMS DMs for high-contrast, high-resolution imaging

SBIR Phase I
Contract # NNX12CE60P

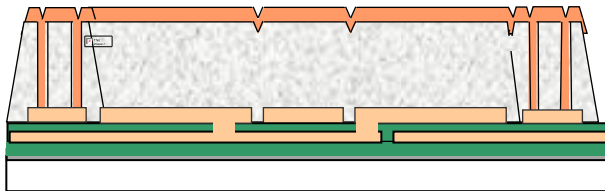


MEMS DM Fabrication

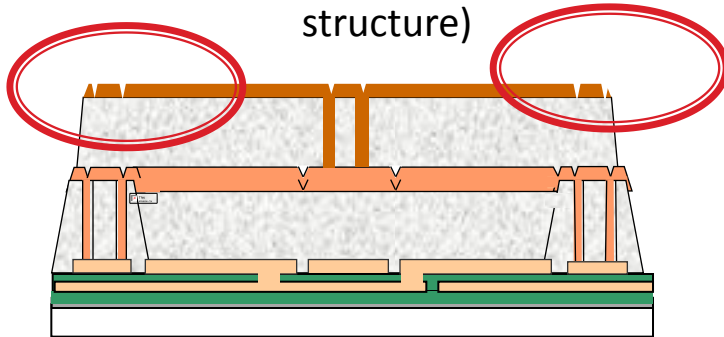
(deposit, pattern, etch, repeat)



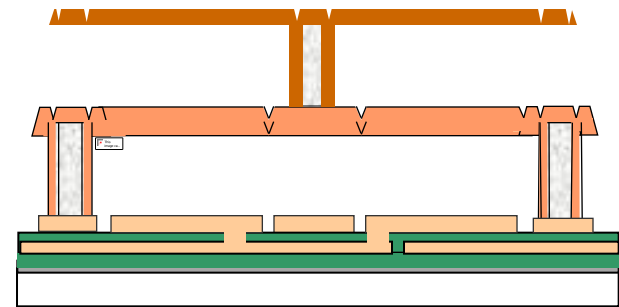
Electrodes & wire traces:
polysilicon (conductor) & silicon nitride (insulator)



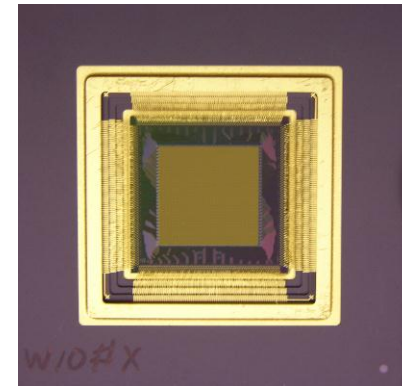
Actuator array:
oxide (sacrificial spacer) and polysilicon (actuator structure)



Mirror membrane:
oxide (spacer) and polysilicon (mirror)



MEMS DM:
Etch away sacrificial oxides in HF, and
deposit reflective coating

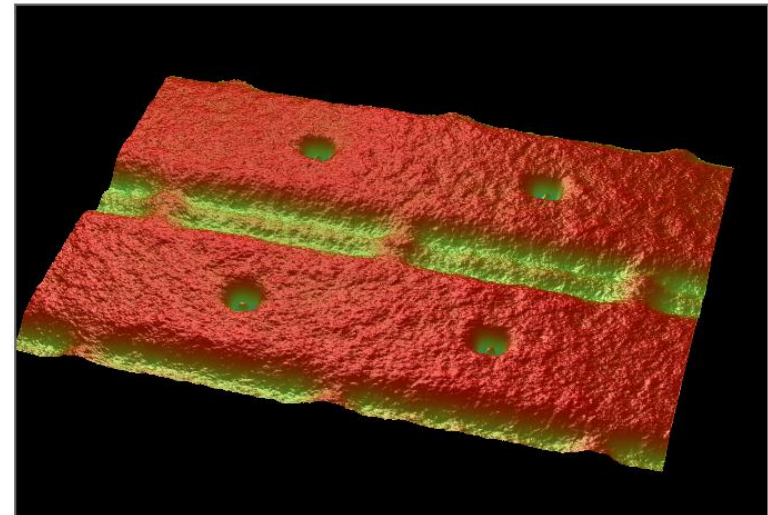


Electrical Interconnects:
Die attach and wirebond to ceramic
chip carrier

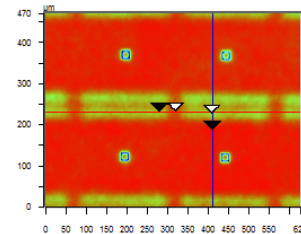
Surface finish of standard polished device



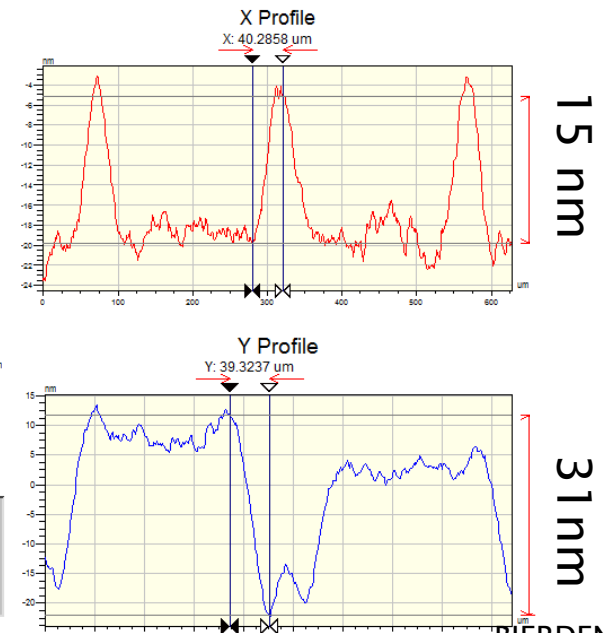
- ▶ $R_q = 9.6\text{nm RMS}$
- ▶ Surface finish from print through areas
- ▶ Small areas outside print through = 1.2nm RMS ($100\mu\text{m} \times 100\mu\text{m}$ area)



Veeco



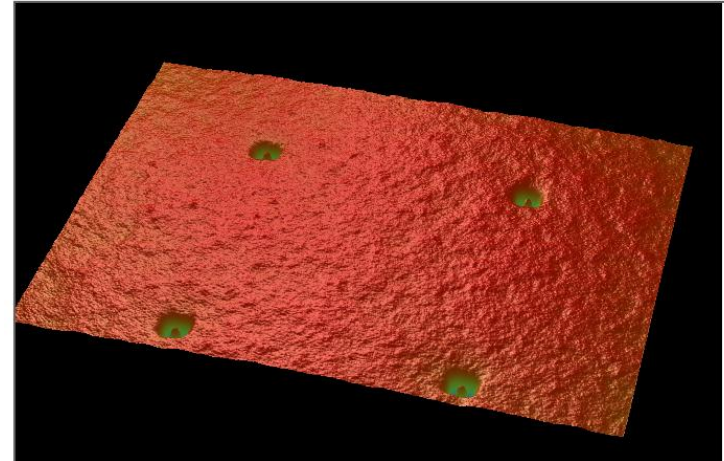
X	410.08	-	-	um
Y	229.56	-	-	um
Ht	-20.08	-	-	nm
Dist		-	-	um
Angle		-	-	°



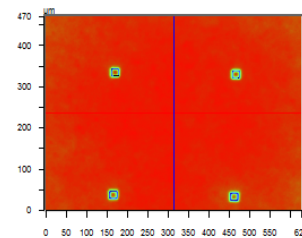


Surface finish of modified process

- ▶ $R_q = 2.2\text{nm RMS}$
- ▶ Combination of fabrication process, new polishing approach, and anneal modifications resulted in elimination of print through



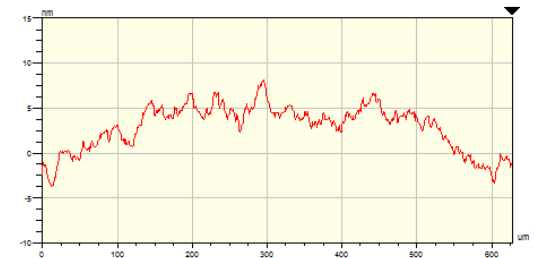
Veeco



X	313.93	-	-	um
Y	235.45	-	-	um
Ht	4.47	-	-	nm
Dist	-	-	-	um
Angle	-	-	-	°

Title:

X Profile



Y Profile





Compact Low-Power Driver for Deformable Mirror Systems

SBIR Phase II

Contract #NNX11CB22C

Multiplexed DM Drive Electronics



- ▶ Existing DM drive electronics using single DAC and amplifiers for each DM drive channel
- ▶ MEMS DM actuator is a capacitor – most power consumed driving high voltage amplifiers & DACs
- ▶ Space-based platforms require low power, more compact , and light weight electronics

Existing MEMS DM Driver Specification

- # Channels: 4,096 channels
 - Power Consumption: 80W (typ)
 - Resolution: 14 & 16-bit
 - Mass (w/ cables): 13.6kg
 - Max Frame Rate: 24kHz
 - Size: 3U Chassis (5.25" x19" x14")
- ▶ We are developing DM drive electronics with a 100x reduction in power consumption and 16-bit (40pm) precision

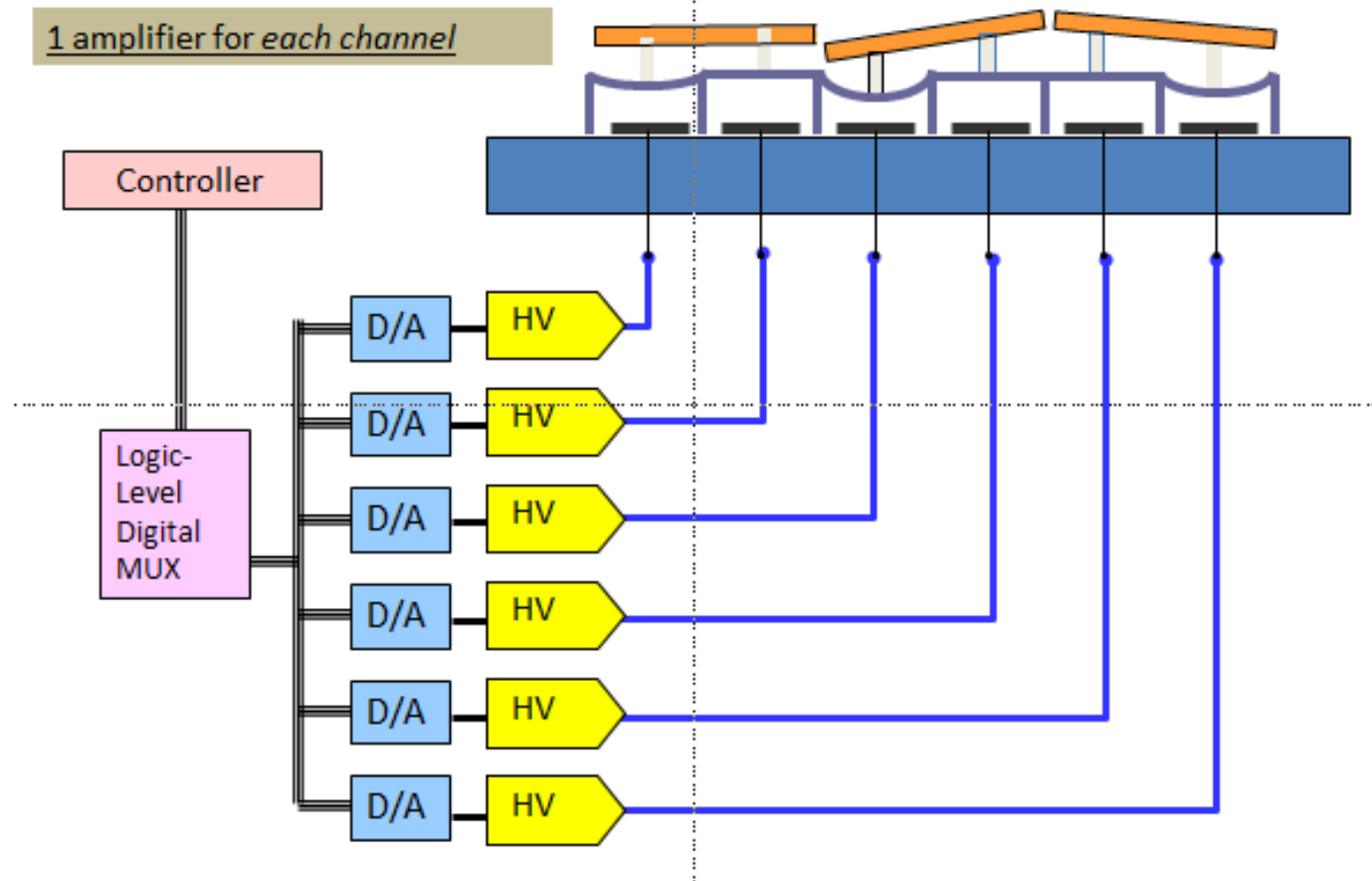


Reduction in SWAP of driver

(Size Weight and Power)

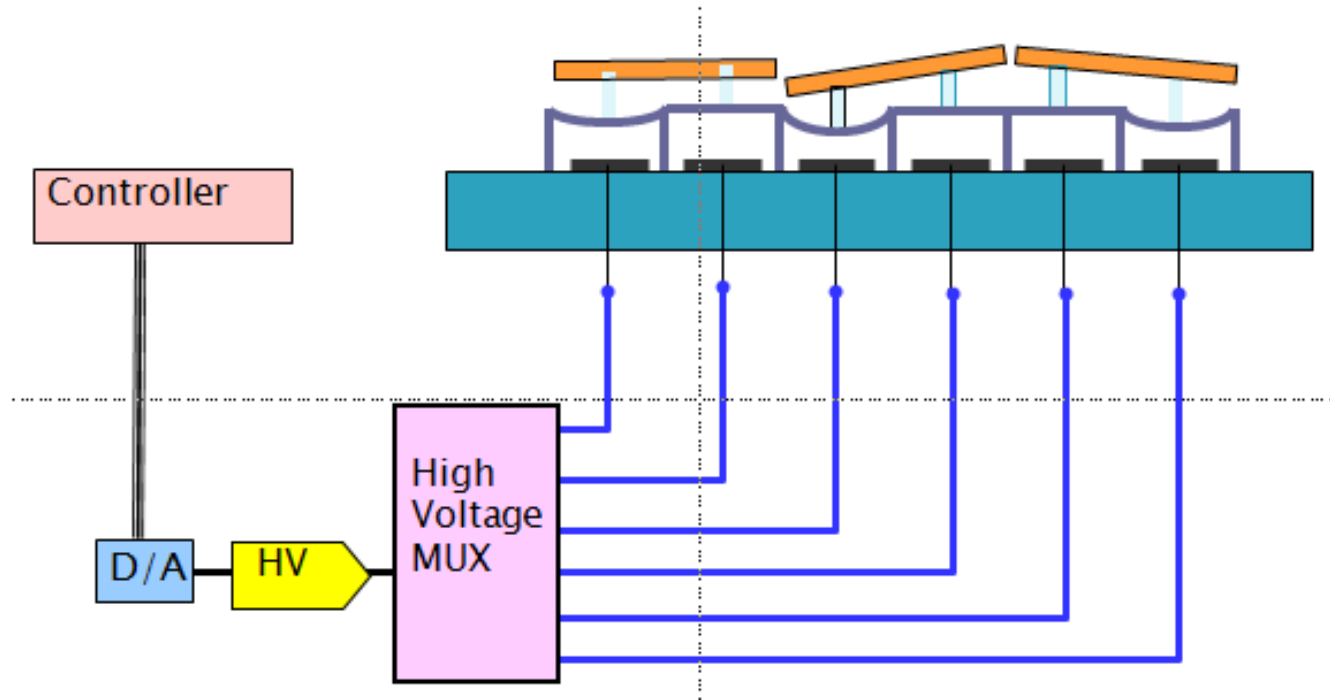
Heritage DM Drive Electronics Architecture

1 amplifier for each channel





Multiplexed DM Drive Electronics Architecture

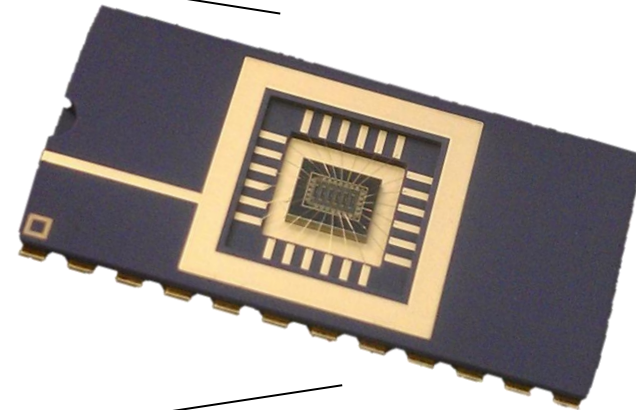
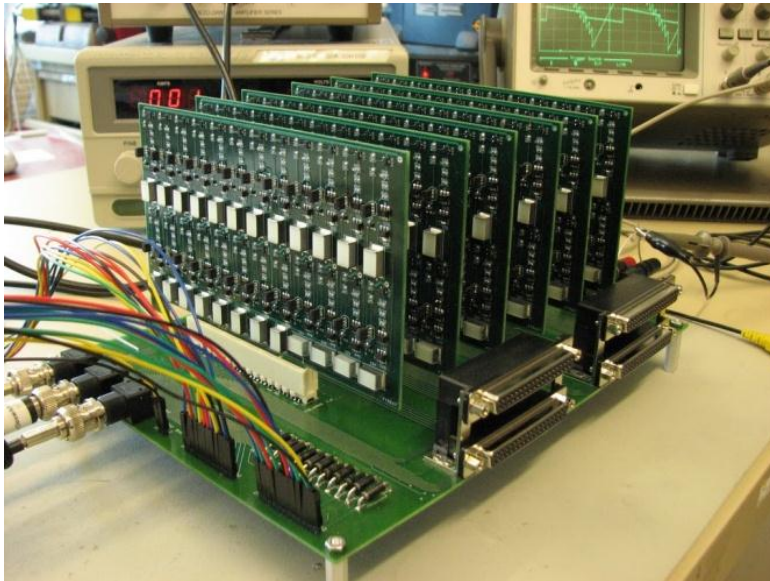


1 amplifier for *entire system*

5mW per Channel

Multiplexed Drive Electronics

- Prototype multiplexed drive electronics developed
 - 16-bit resolution/ $<10\text{pm}$ step size
 - Integrated into HV ASICs for ultra compact form factor
 - DALSA CMOSP8G/HighVoltage Process
 - First Prototype Chips (small channel count) in and testing





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MEMS Deformable Mirror Technology Development for Space-Based Exoplanet Detection

TDEM

Contract # Imminent

Selected for contract, but not signed



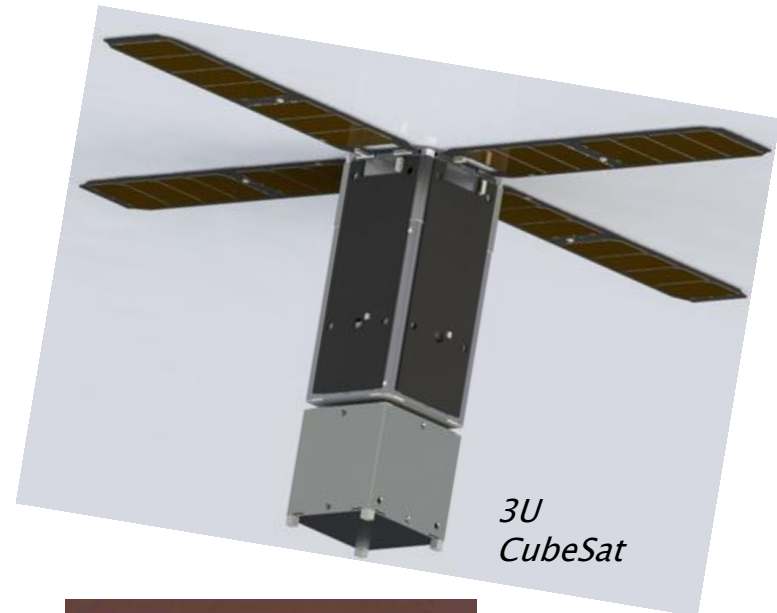
TDEM Program

- ▶ Fabricate and characterize 1k actuator continuous-surface and tip-tilt-piston devices (18 devices)
- ▶ Distribute to test beds for characterization
 - Goddard: Visible Nulling Coronagraph
 - Princeton: High Contrast Imaging Laboratory
 - JPL : ExEP laboratory
- ▶ Environmental testing at Goddard Environmental Test & Integration Facilities
 - Shock/Vibe
 - Acoustic
 - Thermal-Vac
- ▶ Re-characterize at test beds

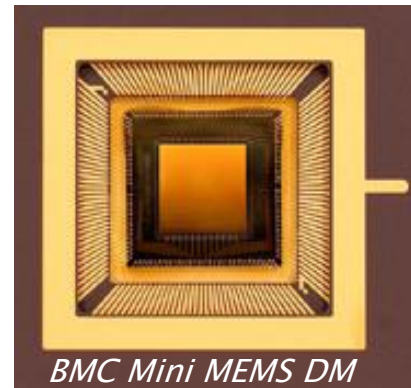
CubeSat MEMS Deformable Mirror Demonstration

Characterization of a Wavefront
Control system on-orbit

Long duration operation in
space environment, software
and microcontroller,
operations, data
management



- ▶ Dr. Keri Cahoy, MIT
- ▶ Boeing Assistant Professor
Department of Aeronautics
and Astronautics





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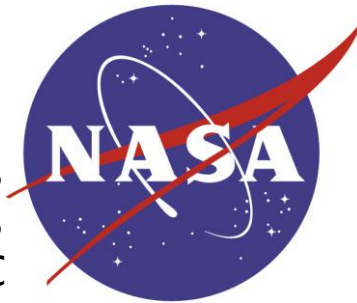
Conclusion



Boston Micromachines Corporation is advancing MEMS deformable mirror technology to meet needs for spaced based Adaptive Optics systems through NASA's SBIR program

Acknowledgements

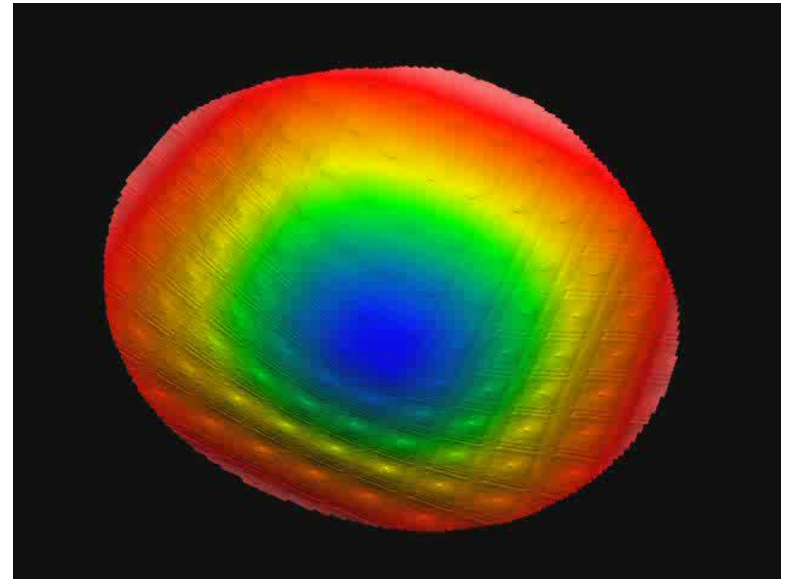
- ▶ Funding from NASA/JPL
 - SBIR Phase I/II # NNX10CE09P/NNX11CB
 - SBIR Phase I /II# NNX10CE08P/NNX11CB
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- ▶ M. Horenstein at Boston University Photonics Center





Thank You

Questions?



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